# 2SJ0582

## Silicon P-channel power MOSFET

#### ■ Features

- Avalanche energy capability guaranteed
- High-speed switching
- No secondary breakdown

#### Applications

- Non-contact relay
- Solenoid drive
- Motor drive
- Control equipment
- Switching mode regulator

### ■ Absolute Maximum Ratings $T_C = 25$ °C

| Parameter                      | Symbol           | Rating      | Unit |
|--------------------------------|------------------|-------------|------|
| Drain-source surrender voltage | V <sub>DSS</sub> | -200        | V    |
| Gate-source surrender voltage  | V <sub>GSS</sub> | ±20         | V    |
| Drain current                  | $I_D$            | ±2          | A    |
| Peak drain current             | $I_{DP}$         | ±4          | A    |
| Avalanche energy capability *  | EAS              | 10          | mJ   |
| Power dissipation              | $P_{\mathrm{D}}$ | 10          | W    |
| $T_a = 25^{\circ}C$            |                  | 1           |      |
| Channel temperature            | T <sub>ch</sub>  | 150         | °C   |
| Storage temperature            | T <sub>stg</sub> | -55 to +150 | °C   |

Note) \*: L = 5 mH,  $I_L = 2$  A, 1 pulse

### ■ Package

• Code U-G2

• Pin Name

1: Gate

2: Drain

3: Source

■ Marking Symbol: J0582

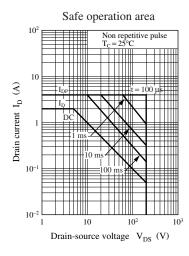
#### ■ Internal Connection

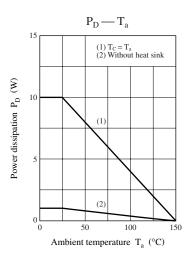


## ■ Electrical Characteristics $T_C = 25$ °C $\pm 3$ °C

| Parameter  | Symbol                | Conditions   | Min  | Тур | Max  | Unit |
|--|-----------------------|--|------|-----|------|------|
| Drain-source cutoff current                                | $I_{DSS}$             | $V_{DS} = -160 \text{ V}, V_{GS} = 0$                            |      |     | -10  | μΑ   |
| Gate-source cutoff current                                 | $I_{GSS}$             | $V_{GS} = \pm 20 \text{ V}, V_{DS} = 0$                          |      |     | ±10  | μΑ   |
| Drain-source surrender voltage                             | V <sub>DSS</sub>      | $I_D = -1 \text{ mA}, V_{GS} = 0$                                | -200 |     |      | V    |
| Gate threshold voltage                                     | V <sub>th</sub>       | $V_{DS} = -25 \text{ V}, I_{D} = -1 \text{ mA}$                  | -2.0 |     | -4.0 | V    |
| Drain-source ON resistance                                 | R <sub>DS(on)</sub>   | $V_{GS} = -10 \text{ V}, I_D = -1.0 \text{ A}$                   |      | 1.5 | 2.0  | Ω    |
| Forward transfer admittance                                | Yfs                   | $V_{DS} = -25 \text{ V}, I_{D} = -1.0 \text{ A}$                 | 1.0  | 1.7 |      | S    |
| Diode forward voltage                                      | $V_{\mathrm{DF}}$     | $I_{DR} = -2.0 \text{ A}, V_{GS} = 0$                            |      |     | 1.4  | V    |
| Short-circuit forward transfer capacitance (Common source) | C <sub>iss</sub>      | $V_{DS} = -20 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$          |      | 400 |      | pF   |
| Short-circuit output capacitance (Common source)           | C <sub>oss</sub>      |  |      | 55  |      | pF   |
| Reverse transfer capacitance<br>(Common source)            | C <sub>rss</sub>      |  |      | 25  |      | pF   |
| Turn-on delay time   | t <sub>d(on)</sub>    | $V_{DD} = 100 \text{ V}, I_D = -1.0 \text{ A}, R_L = 100 \Omega$ |      | 12  |      | ns   |
| Rise time  | t <sub>r</sub>        | $V_{GS} = -10 \text{ V}$   |      | 15  |      | ns   |
| Turn-off delay time  | t <sub>d(off)</sub>   |  |      | 50  |      | ns   |
| Fall time  | $t_{\rm f}$           |  |      | 25  |      | ns   |
| Thermal resistance (ch-c)                                  | R <sub>th(ch-c)</sub> |  |      |     | 12.5 | °C/W |
| Thermal resistance (ch-a)                                  | R <sub>th(ch-a)</sub> |  |      |     | 125  | °C/W |

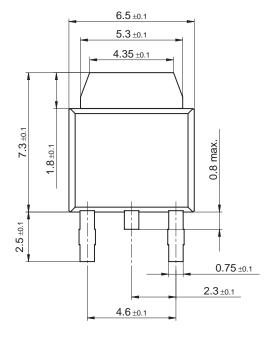
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

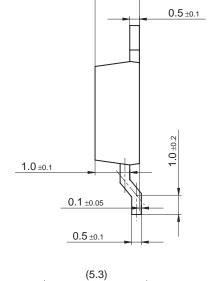




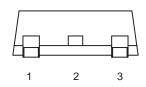
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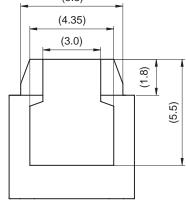
U-G2 Unit: mm





 $2.3{\scriptstyle~ \pm 0.1}$ 





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